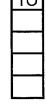
COUNT	DESCRIPTION	OF REVISIO	ONS	BY	CHKD	CHKD DATE		COUNT		DESCRIPTION OF REVISIONS		BY CHKD		DATE	
APPLICA	BLE STAND	ARD													
	E 150 V AC (DC)						CURRENT 1 A					Α			
RATING	OPERATING		35 °C TO ±85 °C(NOTE1) STOR						ORAGE	AGE -10°C TO +60 °C(NO				OTE3	)
KATING	OPERATING	TEMPERATURE RANGE OPERATING			STOR						AGE 40% TO 70% (NO				
	HUMIDITY RA	NGE THOMIL								RANGE	4070		070 (110		
	SPECIFICATIONS														
l l	TEST METHOD								REQUIREMENTS					AT	
CONST															
GENERAL EX	7100/1221100								ACCORDING TO DRAWING.					×	
MARKING		CONFIRMED VISUALLY.												×	
	TERISTICS												Ι×	Τ	
CONTACT R	100 mA (DC OR 1000 Hz).								30 mΩ MAX.						
CONTACT I	20mV MAX, 1mA (DC or 1000Hz).													-	
INSULATION									500 MΩ MIN.						
VOLTAGE PF	100 V DC. 500 V AC FOR 1 min.								NO FLASHOVER OR BREAKDOWN.					<del>                                     </del>	
MECHAI	VICAL CHA	RACTE	RIST	ICS					l					×	L
MECHANICA		50 TIMES INSERTIONS AND EXTRACTIONS.								① CONTACT RESISTANCE: 30 mΩ MAX.					
		·							1 -	② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.					
VIBRATION					GLE AMPLIT	UDE		1	① NO ELECTRICAL DISCONTINUITY OF 1 μs.					1-	
allook	0.75 mm, AT 2 h, FOR 3 DIRECTIONS. 490 m/s <sup>2</sup> DURATION OF PULSE 11 ms AT 3 TIMES FOR 3								NO DAMAGE, C PARTS.	RACK OR LOC	SENE	SS OF			
SHOCK		DIRECTION		ON OF	FULSE	TITISALS	IIVIES	FOR	1	171(10.					
<b>ENVIRO</b>	NMENTAL	CHARA	CTE	RIST	rics										
DAMP HEAT (STEADY ST	EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h.								① CONTACT RESISTANCE: 30 mΩ MAX. ② INSULATION RESISTANCE: 500 MΩ MIN.					-	
RAPID CHAN	TEMPERATURE –55→ 5TO 35→+85→ 5TO 35°C								③ NO DAMAGE, CRACK OR LOOSENESS OF						
TEMPERATURE		TIME 30→10TO 15→ 30→10TO 15min								PARTS.					
RESISTANO	RESISTANCE TO			DERIN	NG				NC	NO DEFORMATION OF CASE OF					_
SOLDERING	SOLDERING HEAT		V AREA		MAV					EXCESSIVE LOOSENESS OF THE					
	MAX 250℃ 10 sec MAX 220℃ MIN 60 sec.MAX  《PREHEATING AREA》								TERMINALS.						
	150 TO 200℃ 60 sec. To 150 sec. PUT THROUGH IN REFLOW FUMACE TWICE.													ŀ	
	ł				ATURE AND	)									
	HUMIDITY FOR 1 HOUR.  CONNECTOR TEMPERATURE TO BE  AMBIENT FOR SECOND REFLOW.  2) MANUAL SOLDERING														
	SOLDER				TURE										
	350℃, FOR 3 sec.														
SOLDERABIL	ITY	NO STRENGTH ON CONTACT.  SOLDERING TEMPERATURE: 230 ± 5°C							A N	NEW UNIFORM (	COATING OF S	OLDEF	R SHALL	X	
		DURATION							VER MINIMUM		IE SUR	FACE	^		
REMARKS			LDERING, FOR 5 sec.  DRAV							BEING IMMERSED.  DESIGNED CHECKED APPROVED					ASED
NOTE1: INCLUDING THE TEMPERATURE RISE NOTE2:NO CONDENSING.															
NOTE3:APPL		N OF LONG TERM STORAGE					ı)		or or le or le						
			TS BEFORE PCB ON BOARD, ERATING TEMPERATURE AND					(. Kumagan		NUX   (. N.UMUYUNU J.MYJOJOGU   J.MYJ		yazosec	1		
HUMII	PPLIED FOR	LIED FOR INTERIM STORAGE					U		$ \cdot $	· · ·	, ,				
DURII Unless othe		o JIS C 5402.					7. Kumaganva 7. Kumagawa <i>T. Mujayaké</i> '04.11.18 '04.11.18 64.11.19			04	/////				
	ualification Test				×:Ap <sub>l</sub>	olicable Tes							, <u>,                                   </u>		
HRS.	HIROSE EL	ECTRIC (	ന ദ	TD	SP	ECIFIC.	ATI	ON :	SHE	ET PART N		. D.	.1 25\	1/77	' <b>\</b>
CODE NO.(O			RAWIN		<u> </u>			Īr	PART		F13B — *	· r –	1.25	11)	<del>í</del>
13332 110.00	,	الا				3670-	44	[			CL536-				1/



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